

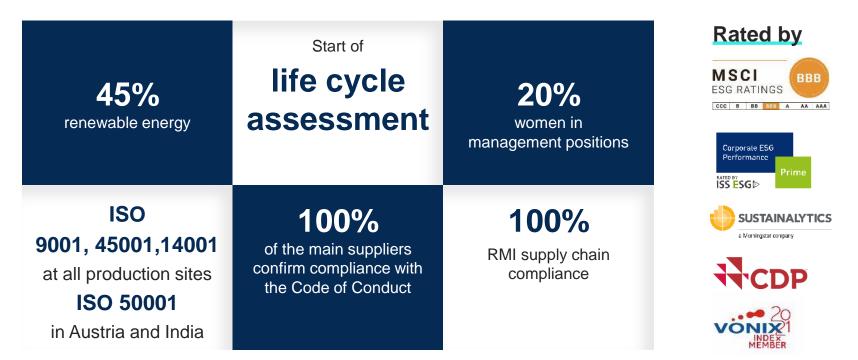
CONSISTENCY IN CHANGE

Erste Group - Innovation Conference 2021

Investor and Analyst Presentation



Highlights FY 20/21





LEADING PROVIDER OF HIGH-END PCBs & IC SUBSTRATES

Well positioned for the future

Unique market position

- Broad product portfolio to serve all growth markets
- Long-standing customer relationships with technology and market leaders
- Technology innovator due to continuous R&D efforts
- Quality benchmark with outstanding process know-how, productivity and efficiency

Growth oriented strategy

- Megatrend-driven markets with attractive growth potential
- Address growth opportunities with incremental investments
- Constant outperformance of the PCB & substrates market

€1.2 bn **>€2 bn** revenue

revenue FY 23/24

5 ABF substrates producer

worldwide

FY 20/21

#3 in FY 24/25

#2 high-end PCB producer worldwide

ONE

of the leading high-end PCB producers worldwide

GLOBAL FOOTPRINT



 AT&S Headquarters

¹ Staff, Average, FTE, FY 20/21; 80 employees in other locations

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MARKET SEGMENTS & PRODUCT APPLICATIONS



Segment Mobile Devices & Substrates

Segment Automotive, Industrial, Medical

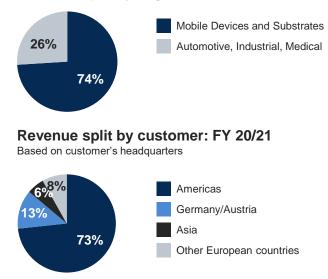




In € mn +10% CAGR 1188 1028 1001 992 815 23% 24% 21% 19% 16% 250 246 226 195 131* 2016/17 2017/18 2018/19 2019/20 2020/21

EBITDA margin

Revenue split by segment: FY 20/21

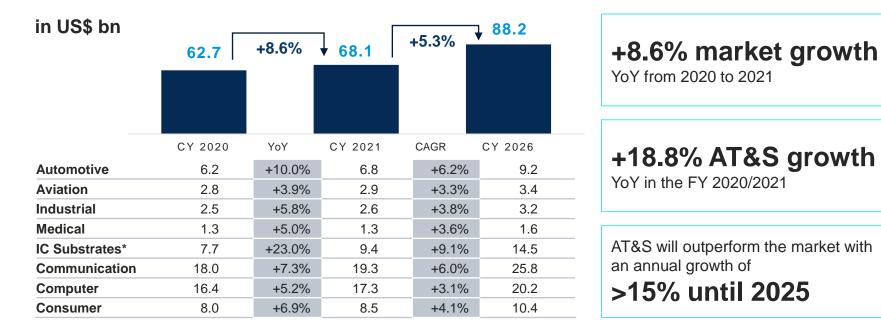


* Based on ramp-up effects for new plants in China

EBITDA

Revenue

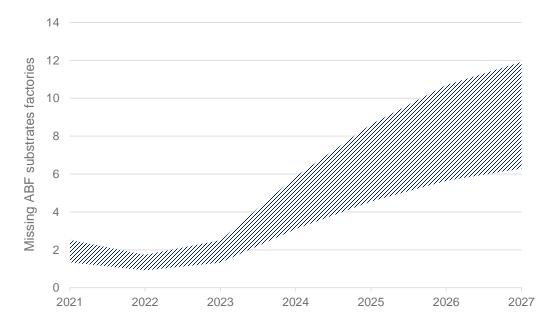
AT&S OUTPERFORMS PCB & IC SUBSTRATES* MARKET GROWTH





CONTINUOUS GROWTH IN ABF SUBSTRATES DEMAND

Actual gap of required ABF substrates factories to satisfy demand



- Actual gap depends on actual mix in product and technology demand
- Increasing complexity of high-end products leads to ongoing strong ABF substrates demand
- Complexity requires increasing layer count and larger products
- Current supply shortage is predominantly in high-end products
- Especially server and Al applications drive the demand

STRATEGIC BUSINESS DRIVERS





GAME CHANGERS ARE DRIVING OUR BUSINESS

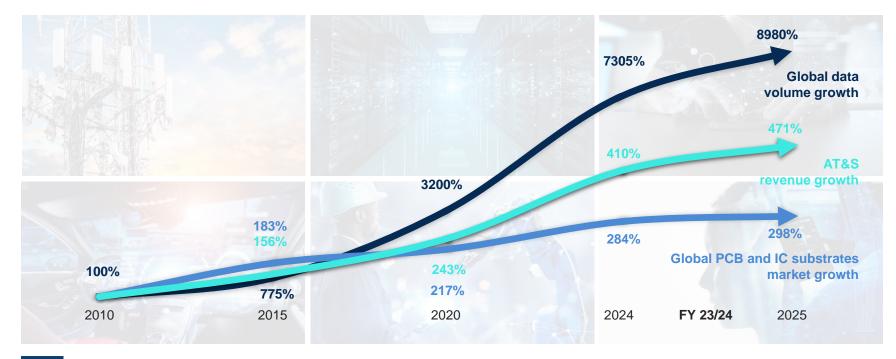
New technologies and systems bring a significant data volume increase





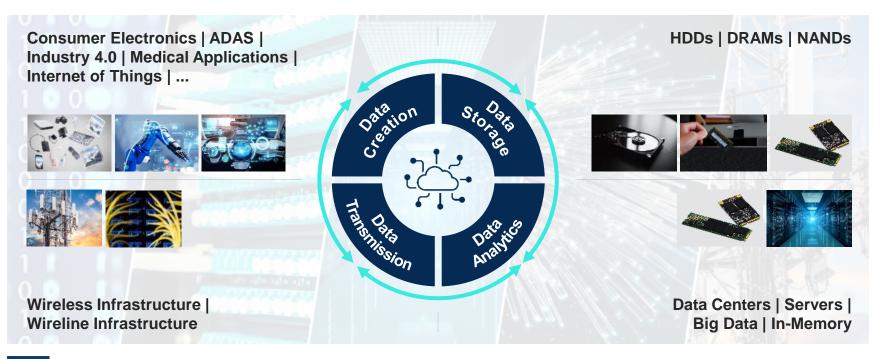


GLOBAL DATA VOLUME DEVELOPMENT DRIVES AT&S GROWTH





DIGITALISATION REQUIRES DATA MANAGEMENT



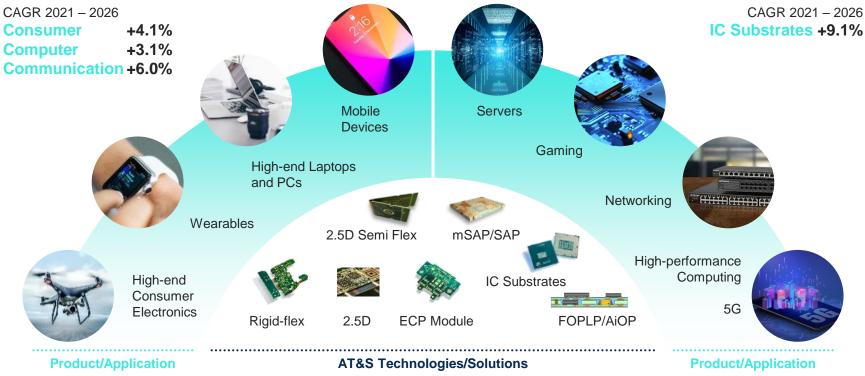


AT&S GROWTH ENABLED BY APPLICATIONS AND INNOVATION & SUSTAINABILITY

Investor and Analyst Presentation



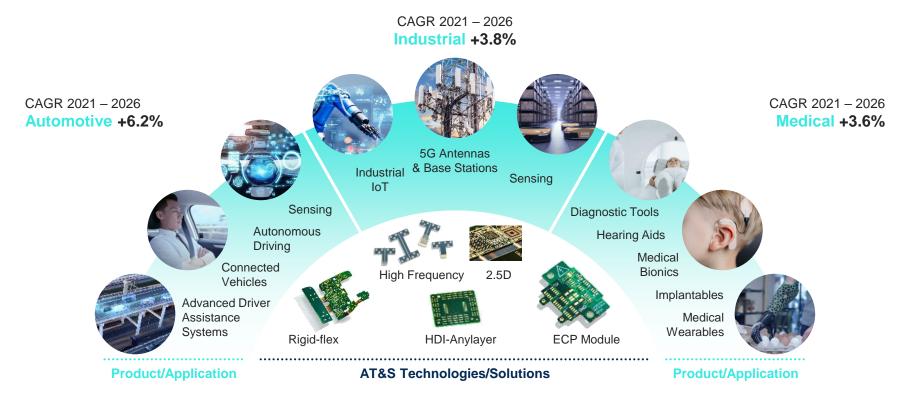
MOBILE DEVICES AND SUBSTRATES



* PCB/IC Substrates Market Growth: CAGR 2021-2026



AUTOMOTIVE – INDUSTRIAL – MEDICAL





R&D – BASIS FOR TECHNOLOGY LEADERSHIP



Status: FY 2020/21

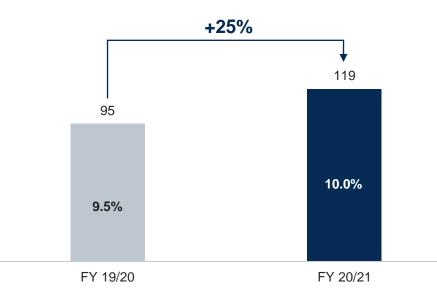
*Share of revenue of technologically innovative products made in the last three years (previously: Innovation Revenue Rate)



R&D INVESTMENTS

A key revenue and margin driver

in € mn

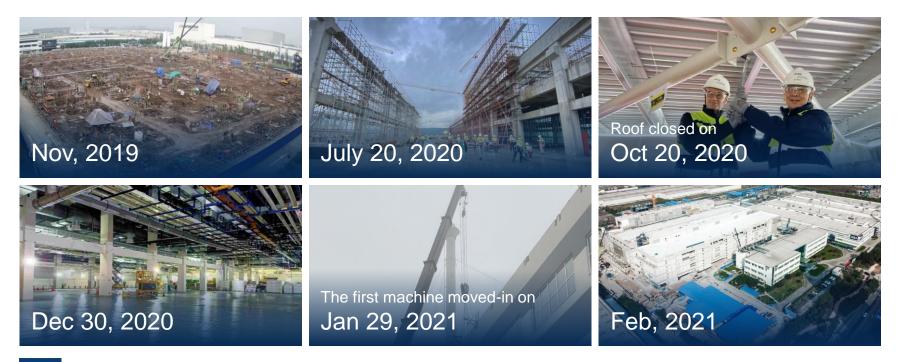


€ 246 mn revenue with new products

Miniaturisation and functional integration	Fast signal transmission
Performance and performance efficiency	Manufacturing of the future

CAPACITY EXPANSION AT CHONGQING III

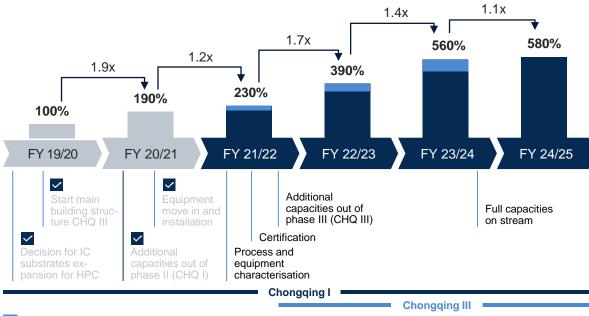
On the way to becoming one of the leading high-end ABF substrates producers





RAMP OF CHONGQING III EARLIER THAN EXPECTED

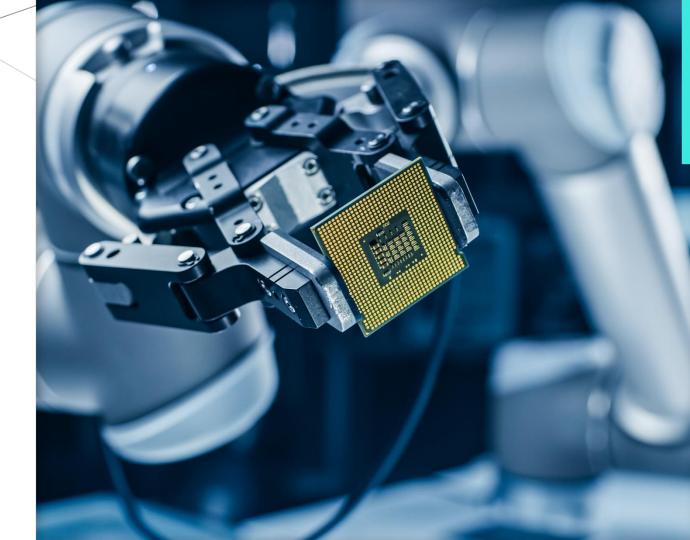
ABF substrates output capacity



Additional output capacity due to investment increase and earlier production start in CHQ III

- CHQ III: Production will already be starting in FY 21/22
- Additional € 200 mn investment in CHQ III
- Full capacities available with the beginning of CY 2024 (Q4 23/24)

RESULTS FY 20/21



KEY DEVELOPMENTS FY 20/21

Strong full-year results demonstrate AT&S resilience and agility

Growing profitably with served markets

- Additional capacities and strong demand drive ABF substrates business
- Mobile applications supported by customer and application diversification
- PCBs for modules contribute to overall revenue growth
- Automotive with ongoing recovery and Q4 above last year
- Medical & Healthcare with stable performance due to improved demand
- Industrial segment with positive development thanks to better product mix
- Capacity expansion in Chongqing faster than expected



FY 20/21 RESULTS SUMMARY

Revenue at historic high

Revenue +19%

€1,188 mn

- Five year CAGR 8%
- Negative FX effects of € 37 mn

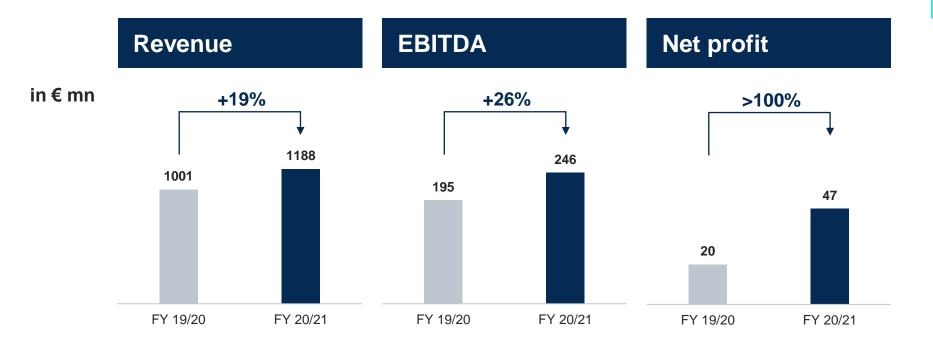
EBITDA margin **+130 bps**

 Strong EBITDA margin despite headwinds from COVID-19 impacts ROCE +300 bps

 Driven by strong operating result

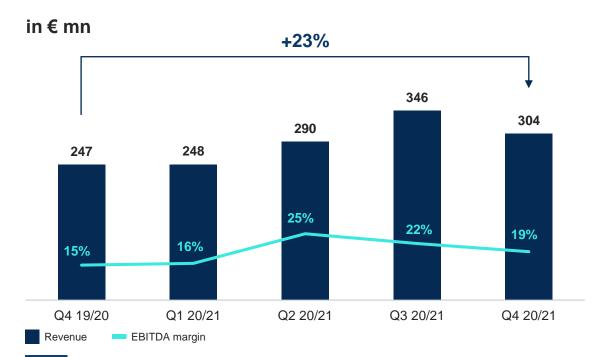


FY 20/21 RESULTS SUMMARY





QUARTERLY DEVELOPMENT



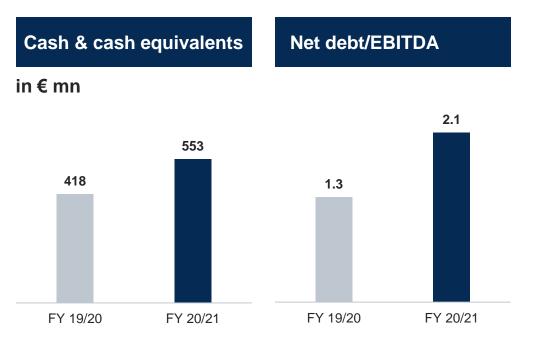
Highest Q4 revenue in history

Part of **seasonality mitigated** by growing IC substrates business

Profitability clearly improved

FY 20/21 FINANCIAL POSITION

Solid financial structure for future growth



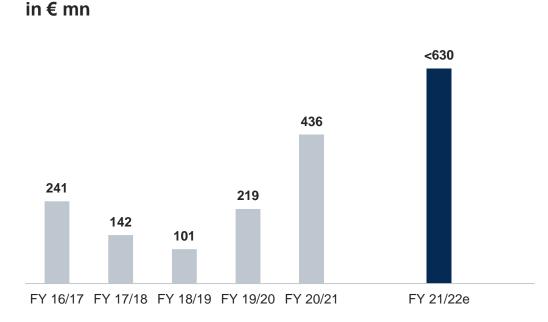
Balancing capital allocation

- Deploying capital with clear approach to invest in strategic growth markets
- Increasing net debt level by € 262 m in FY 20/21 due to investments in additional IC substrates capacities

Sound investment decisions to generate strong operating and free cash flow in the future.

NET CAPEX

Investments in IC substrates and module PCBs consistently continued



Capex outlook 2021/22

- Depending on market developments CAPEX for maintenance and tech upgrade of up to € 100 m
- CAPEX for strategic projects of up to € 450 m plus € 80 m due to timing variances

BALANCE SHEET

€mn	31.03.2020	31.03.2021	Change in %	
Total assets	1,854	2,390	+29%	Ongoing expansion and technology upgrades main driver for increase in total assets
Equity	760	802	+6%	
Equity ratio	41%	34%	-740bps	Increase in total assets weighs on equity ratio
Net debt	247	509	>100%	Higher CAPEX feeds into liquidity and drives up net debt

GUIDANCE FY 21/22

Further growth ahead

FY 21/22		
Growth	Revenue growth of 13 – 15%	
Profitability	Adjusted EBITDA margin of 21 – 23% Adjustment: start-up effects of the Chongqing project with an amount of appr. € 40 mn	
CAPEX	 Maintenance and tech-upgrades € 100 mn CAPEX from PY (timing variances) € 80 mn Expansion projects € 450 m 	
Dividend proposal	€ 0.39 per share (for FY 20/21)	



MEDIUM-TERM GUIDANCE

Technology development to module integration and capacity expansion

First choice for advanced applications

Expansion of technology leadership

- Leading provider of new interconnect solutions
- Innovation revenue rate: > 20%

Focus on continued profitable growth

- 2023/24: Revenue target of more than € 2 bn
- 2023/24: EBITDA margin target of 25 30%

Creation of shareholder value and robust financial structure

- Medium-term ROCE above 12%
- Net debt / EBITDA: < 3/Equity ratio: > 40%/Average Finance costs: < 2%</p>

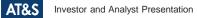
Sustainability management

- 80% renewable energy
- Eco-balancing of product groups
- 30% women in management positions









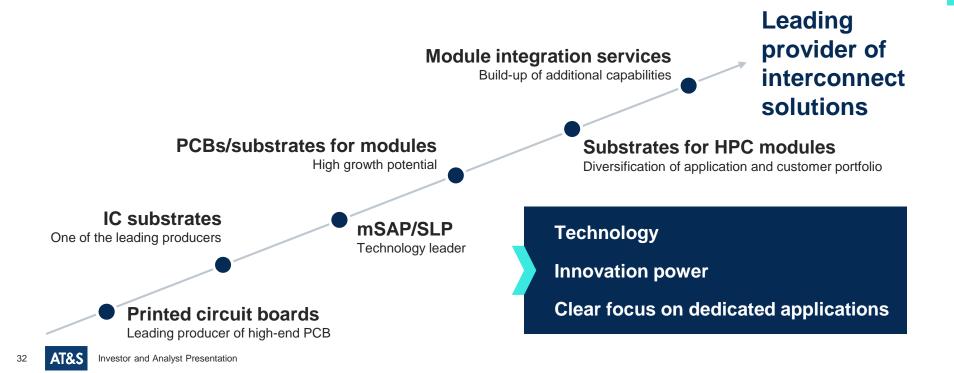
MARKET PLAYERS IN THE HIGH-END SEGMENT

HDI Technology (2019)		ABF Substrates (2019)	
1	Compeq	1	Ibiden
2	AT&S	2	Unimicron
3	TTM	3	SEMCO
4	Unimicron	4	Shinko
5	Tripod	5	AT&S
6	Meiko	6	Kyocera
7	Zhen Ding	7	Nan Ya PCB
8	Korea Circuit	8	Kinsus

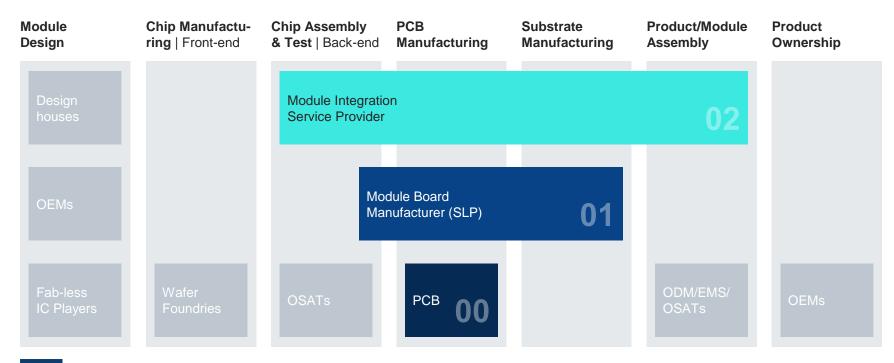
Source: Prismark, JMS, AT&S assessment

MORE THAN AT&S

Broadening the service range and opening up of new business opportunities

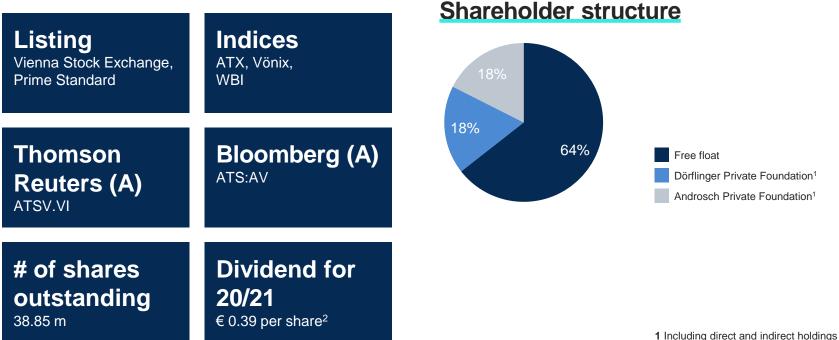


AT&S SOLUTIONS FOR THE ELECTRONICS INDUSTRY





AT&S – STOCK PROFILE





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